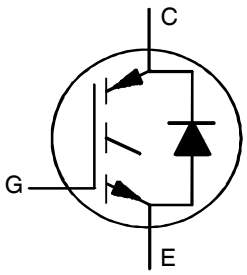
International
IOR Rectifier

IRG7PH35UD1PbF
IRG7PH35UD1-EP

INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRA-LOW VF DIODE FOR INDUCTION HEATING AND SOFT SWITCHING APPLICATIONS

Features

- Low $V_{CE\ (ON)}$ trench IGBT Technology
- Low Switching Losses
- Square RBSOA
- Ultra-Low V_F Diode
- 1300Vpk Repetitive Transient Capacity
- 100% of the Parts Tested for I_{LM} ①
- Positive $V_{CE\ (ON)}$ Temperature Co-Efficient
- Tight Parameter Distribution
- Lead Free Package



n-channel

V_{CES} = 1200V

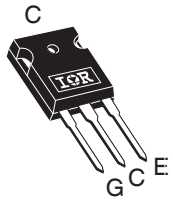
$I_{NOMINAL}$ = 20A

$T_{J(max)}$ = 150°C

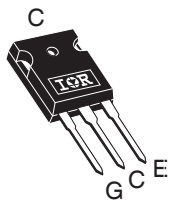
$V_{CE(on)}$ typ. = 1.9V

Benefits

- Device optimized for induction heating and soft switching applications
- High Efficiency due to Low $V_{CE(on)}$, low switching losses and Ultra-low V_F
- Rugged transient performance for increased reliability
- Excellent current sharing in parallel operation
- Low EMI



TO-247AC
IRG7PH35UD1PbF



TO-247AD
IRG7PH35UD1-EP

G	C	E
Gate	Collector	Emitter

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	1200	V
I_C @ T_C = 25°C	Continuous Collector Current	50	A
I_C @ T_C = 100°C	Continuous Collector Current	25	
$I_{NOMINAL}$	Nominal Current	20	
I_{CM}	Pulse Collector Current, V_{GE}=15V ② ⑤	150	
I_{LM}	Clamped Inductive Load Current, V_{GE}=20V ①	80	
I_F @ T_C = 25°C	Diode Continous Forward Current	50	
I_F @ T_C = 100°C	Diode Continous Forward Current	25	
I_{FM}	Diode Maximum Forward Current ②	80	
V_{GE}	Continuous Gate-to-Emitter Voltage	±30	V
P_D @ T_C = 25°C	Maximum Power Dissipation	179	W
P_D @ T_C = 100°C	Maximum Power Dissipation	71	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw	10 lbf·in (1.1 N·m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$ (IGBT)	Thermal Resistance Junction-to-Case-(each IGBT) ④	—	—	0.70	°C/W
$R_{\theta JC}$ (Diode)	Thermal Resistance Junction-to-Case-(each Diode) ④	—	—	1.35	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink (flat, greased surface)	—	0.24	—	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (typical socket mount)	—	40	—	

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	1200	—	—	V	V_{GE} = 0V, I_C = 100µA ③
$V_{(BR)Transient}$	Repetitive Transient Collector-to-Emitter Voltage	—	—	1300	V	V_{GE} = 0V, T_J = 75°C, PW ≤ 10µs ③
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	1.2	—	V/°C	V_{GE} = 0V, I_C = 1mA (25°C-150°C)
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	—	1.9	2.2	V	I_C = 20A, V_{GE} = 15V, T_J = 25°C
		—	2.3	—		I_C = 20A, V_{GE} = 15V, T_J = 150°C
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	6.0	V	V_{CE} = V_{GE}, I_C = 600µA
gfe	Forward Transconductance	—	22	—	S	V_{CE} = 50V, I_C = 20A, PW = 30µs
I_{CES}	Collector-to-Emitter Leakage Current	—	1.0	100	µA	V_{GE} = 0V, V_{CE} = 1200V
		—	120	—		V_{GE} = 0V, V_{CE} = 1200V, T_J = 150°C
V_{FM}	Diode Forward Voltage Drop	—	1.15	1.26	V	I_F = 20A
		—	1.08	—		I_F = 20A, T_J = 150°C
I_{GES}	Gate-to-Emitter Leakage Current	—	—	±100	nA	V_{GE} = ±30V

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	85	130		I_C = 20A
Q_{ge}	Gate-to-Emitter Charge (turn-on)	—	15	20	nC	V_{GE} = 15V
Q_{gc}	Gate-to-Collector Charge (turn-on)	—	35	50		V_{CC} = 600V
E_{off}	Turn-Off Switching Loss	—	620	850	µJ	I_C = 20A, V_{CC} = 600V, V_{GE} = 15V R_G = 10Ω, L = 200µH,L_S = 150nH, T_J = 25°C Energy losses include tail
$t_{d(off)}$	Turn-Off delay time	—	160	180	ns	I_C = 20A, V_{CC} = 600V, V_{GE} = 15V
t_f	Fall time	—	80	105		R_G = 10Ω, L = 200µH,L_S = 150nH, T_J = 25°C
E_{off}	Turn-Off Switching Loss	—	1120	—	µJ	I_C = 20A, V_{CC} = 600V, V_{GE}=15V R_G = 10Ω, L = 200µH,L_S = 150nH, T_J = 150°C Energy losses include tail
$t_{d(off)}$	Turn-Off delay time	—	190	—	ns	I_C = 20A, V_{CC} = 600V, V_{GE} = 15V
t_f	Fall time	—	210	—		R_G = 10Ω, L = 200µH,L_S = 150nH, T_J = 150°C
C_{ies}	Input Capacitance	—	1940	—	pF	V_{GE} = 0V
C_{oes}	Output Capacitance	—	120	—		V_{CC} = 30V
C_{res}	Reverse Transfer Capacitance	—	40	—		f = 1.0Mhz
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				T_J = 150°C, I_C = 80A V_{CC} = 960V, Vp =1200V Rg = 10Ω, V_{GE} = +20V to 0V

Notes:

① V_{CC} = 80% (V_{CES}), V_{GE} = 20V, R_G = 10Ω.
② Pulse width limited by max. junction temperature.
③ Refer to AN-1086 for guidelines for measuring $V_{(BR)CES}$ safely.
④ R_θ is measured at T_J approximately 90°C.
⑤ FBSOA operating conditions only.

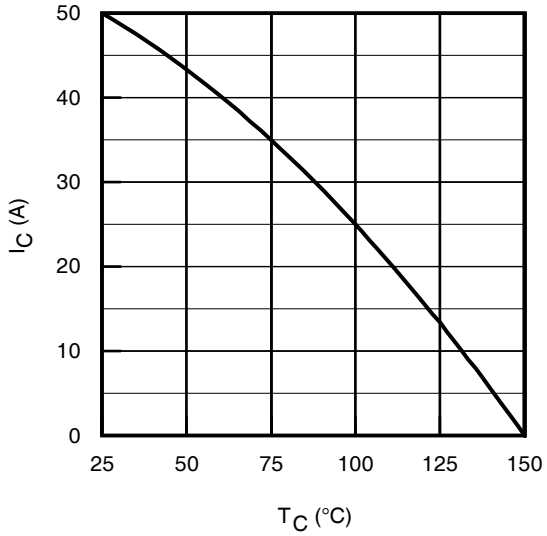


Fig. 1 - Maximum DC Collector Current vs. Case Temperature

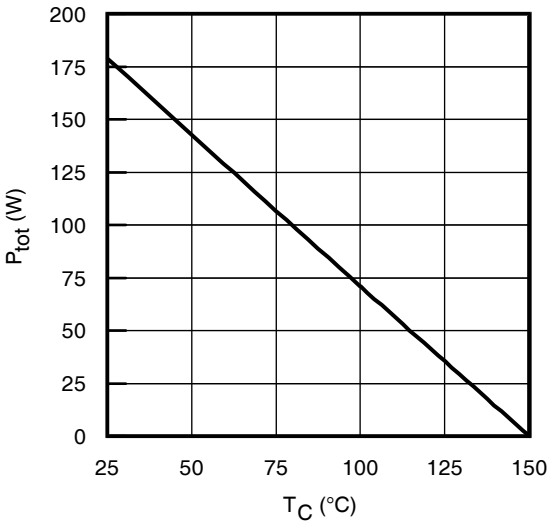


Fig. 2 - Power Dissipation vs. Case Temperature

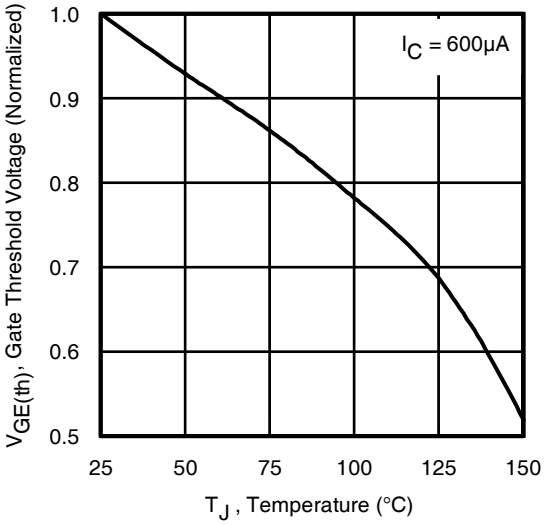


Fig. 3 - Typical Gate Threshold Voltage (Normalized) vs. Junction Temperature

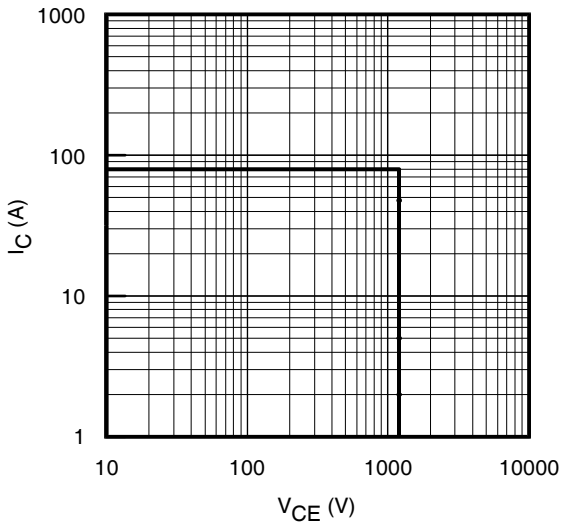


Fig. 4 - Reverse Bias SOA
T_J = 150°C; V_{GE} = 20V

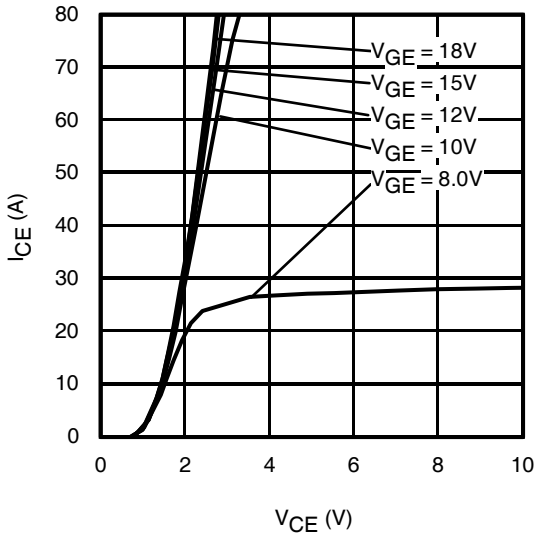


Fig. 5 - Typ. IGBT Output Characteristics
T_J = -40°C; tp = 30µs

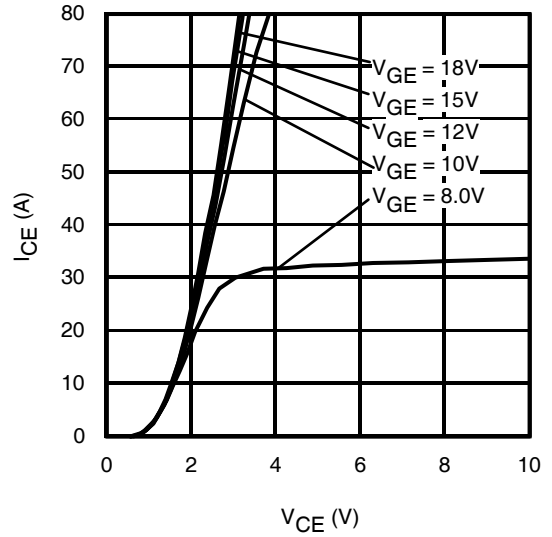


Fig. 6 - Typ. IGBT Output Characteristics
T_J = 25°C; tp = 30µs

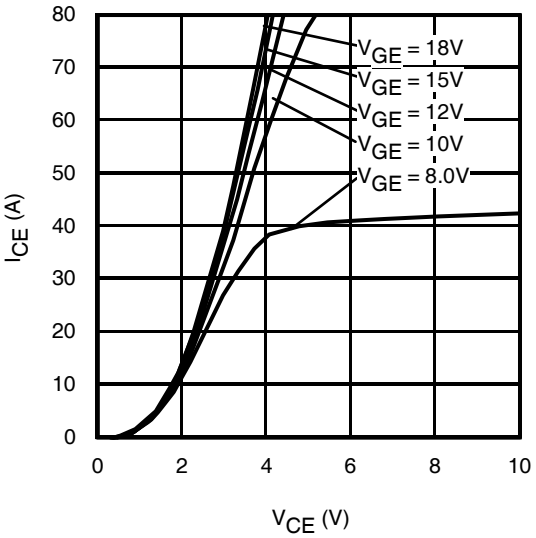


Fig. 7 - Typ. IGBT Output Characteristics
T_J = 150°C; tp = 30µs

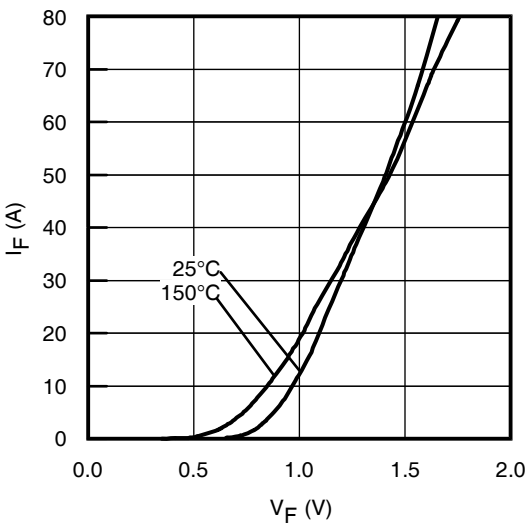


Fig. 8 - Typ. Diode Forward Voltage Drop Characteristics

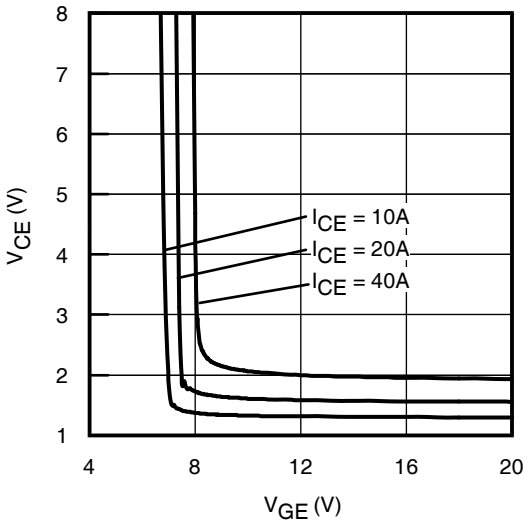


Fig. 9 - Typical V_{CE} vs. V_{GE}
T_J = -40°C

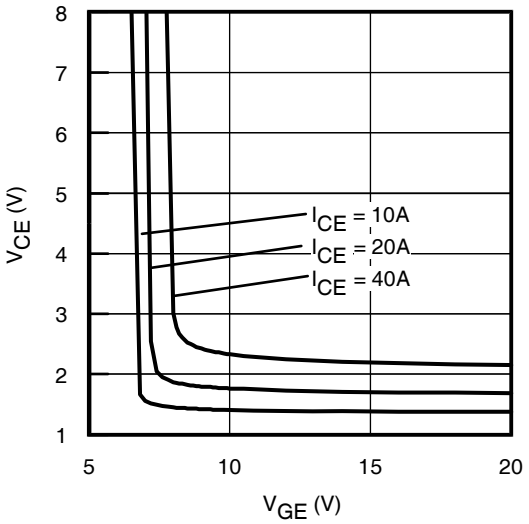


Fig. 10 - Typical V_{CE} vs. V_{GE}
T_J = 25°C

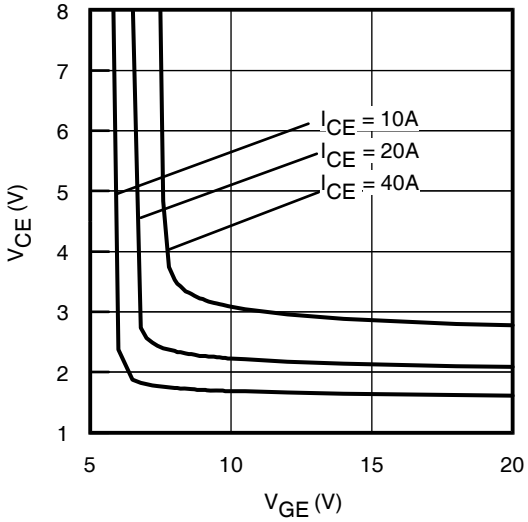


Fig. 11 - Typical V_{CE} vs. V_{GE}
T_J = 150°C

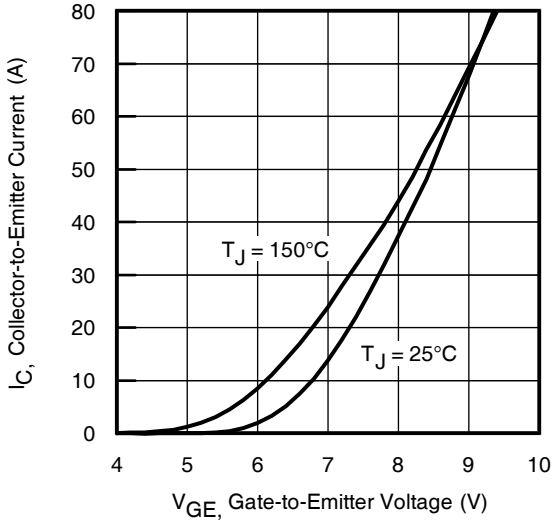


Fig. 12 - Typ. Transfer Characteristics
V_{CE} = 50V; tp = 30µs

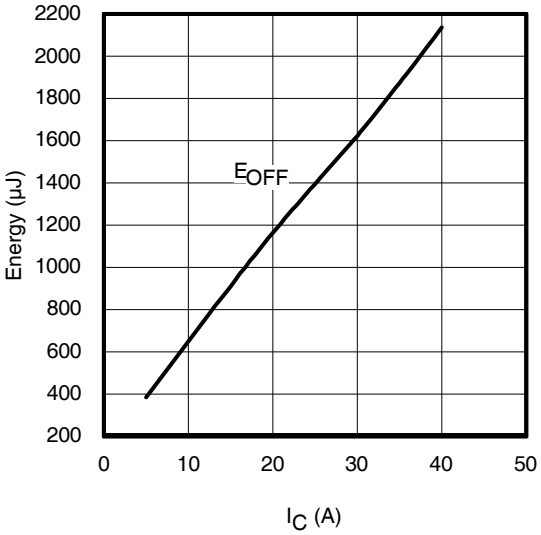


Fig. 13 - Typ. Energy Loss vs. I_C
T_J = 150°C; L = 680µH; V_{CE} = 600V, R_G = 10Ω; V_{GE} = 15V

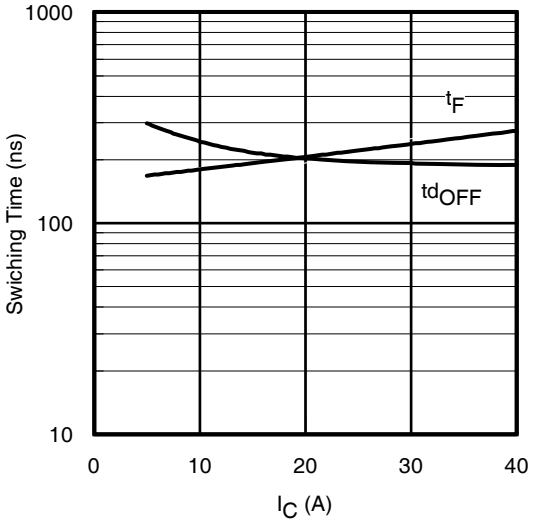


Fig. 14 - Typ. Switching Time vs. I_C
T_J = 150°C; L = 680µH; V_{CE} = 600V, R_G = 10Ω; V_{GE} = 15V

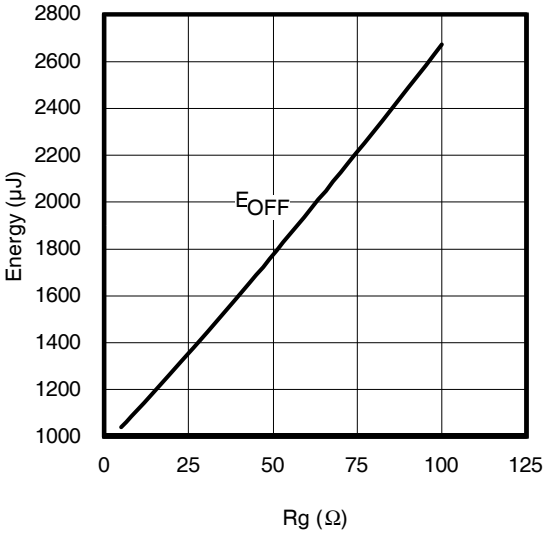


Fig. 15 - Typ. Energy Loss vs. R_G
T_J = 150°C; L = 680µH; V_{CE} = 600V, I_{CE} = 20A; V_{GE} = 15V

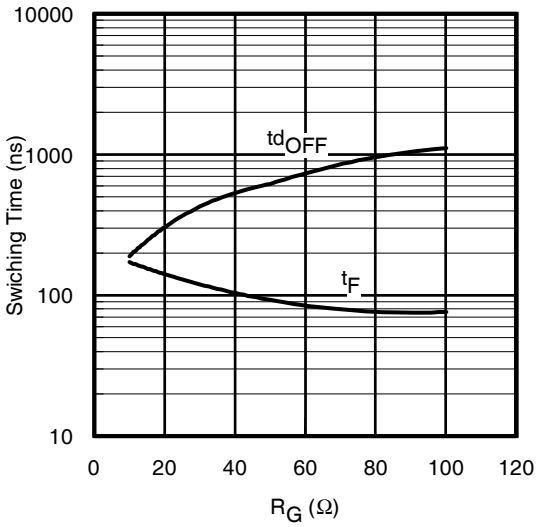


Fig. 16 - Typ. Switching Time vs. R_G
T_J = 150°C; L = 680µH; V_{CE} = 600V, I_{CE} = 20A; V_{GE} = 15V

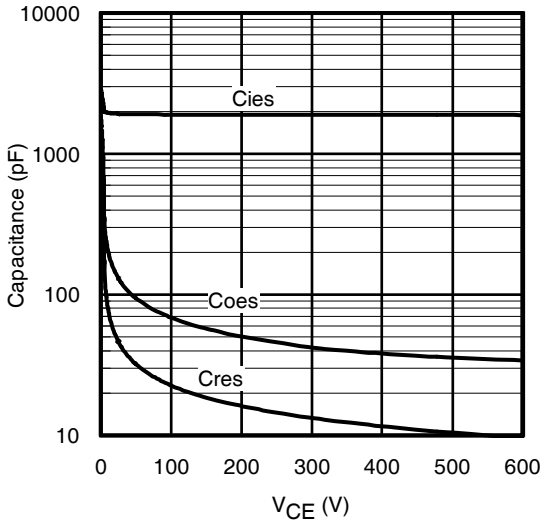


Fig. 17 - Typ. Capacitance vs. V_{CE}
V_{GE}= 0V; f = 1MHz

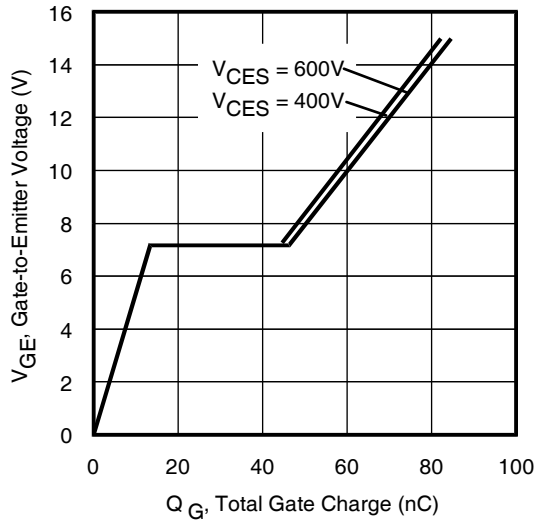


Fig. 18 - Typical Gate Charge vs. V_{GE}
I_{CE} = 20A; L = 2.4mH

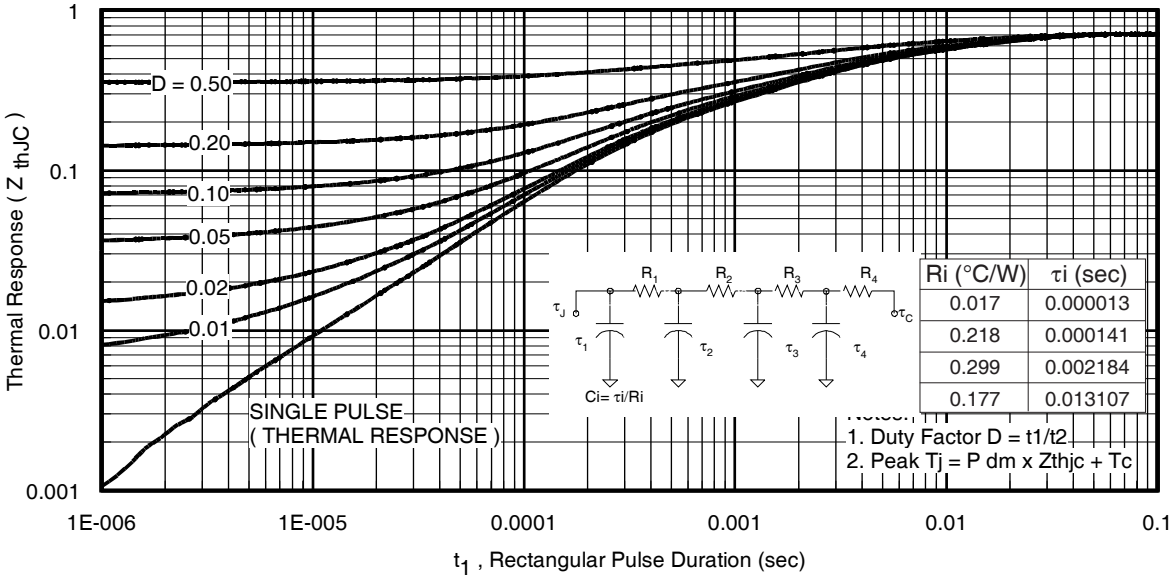


Fig 19. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

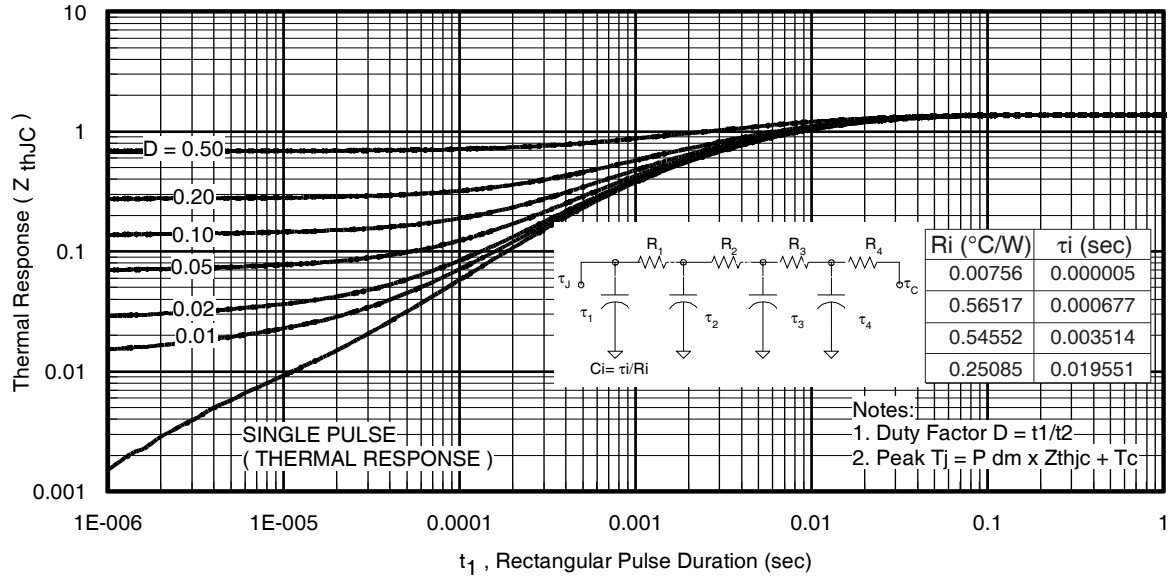


Fig. 20. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

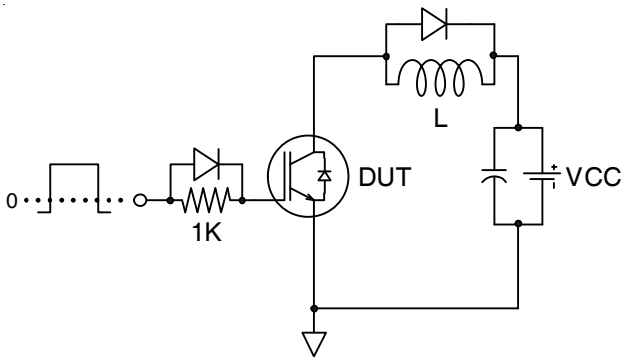


Fig.C.T.1 - Gate Charge Circuit (turn-off)

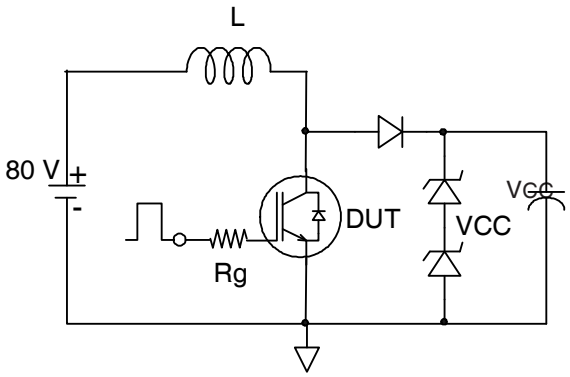


Fig.C.T.2 - RBSOA Circuit

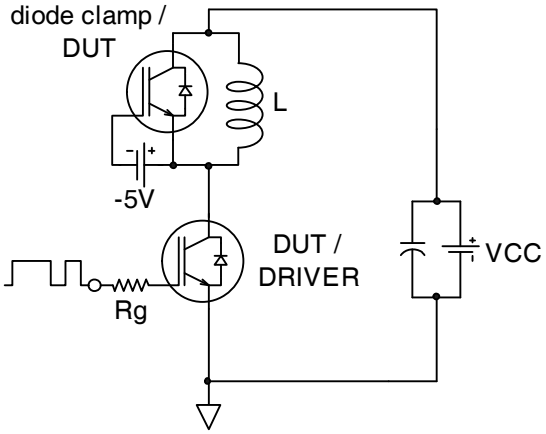


Fig.C.T.3 - Switching Loss Circuit

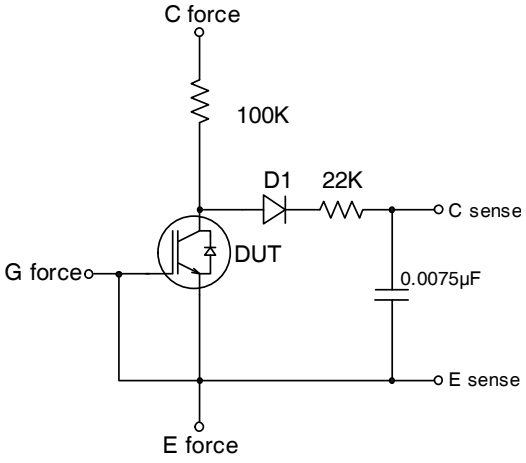


Fig.C.T.4 - BVCES Filter Circuit

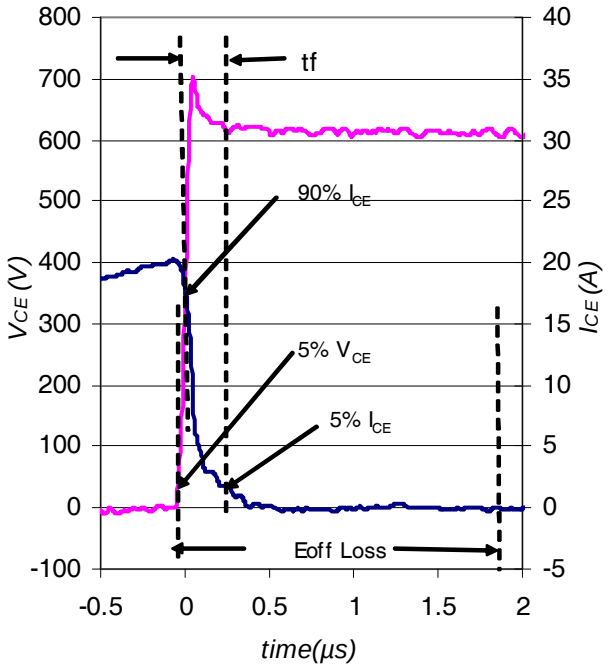
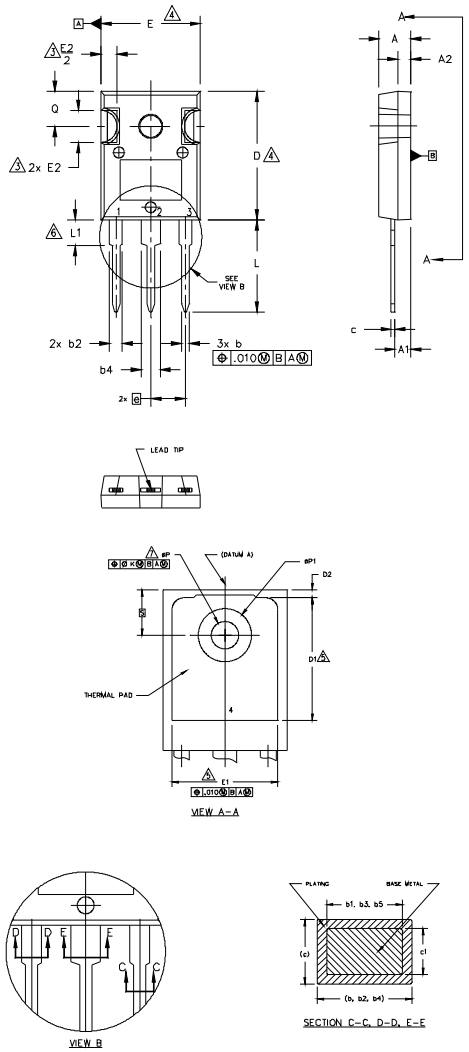


Fig. WF1 - Typ. Turn-off Loss Waveform
@ T_J = 150°C using Fig. CT.3

TO-247AC Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M 1994.
2. DIMENSIONS ARE SHOWN IN INCHES.
3. CONTOUR OF SLOT OPTIONAL.
4. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS D1 & E1.
6. LEAD FINISH UNCONTROLLED IN L1.
7. øP TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5 ° TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF .154 INCH.
8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-247AC .

SYMBOL	DIMENSIONS				NOTES
	INCHES		MILLIMETERS		
	MIN.	MAX.	MIN.	MAX.	
A	.183	.209	4.65	5.31	
A1	.087	.102	2.21	2.59	
A2	.059	.098	1.50	2.49	
b	.039	.055	0.99	1.40	
b1	.039	.053	0.99	1.35	
b2	.065	.094	1.65	2.39	
b3	.065	.092	1.65	2.34	
b4	.102	.135	2.59	3.43	
b5	.102	.133	2.59	3.38	
c	.015	.035	0.38	0.89	
c1	.015	.033	0.38	0.84	
D	.776	.815	19.71	20.70	4
D1	.515	–	13.08	–	5
D2	.020	.053	0.51	1.35	
E	.602	.625	15.29	15.87	4
E1	.530	–	13.46	–	
E2	.178	.216	4.52	5.49	
e	.215 BSC		5.46 BSC		
øk	.010		0.25		
L	.559	.634	14.20	16.10	
L1	.146	.169	3.71	4.29	
øP	.140	.144	3.56	3.66	
øP1	–	.291	–	7.39	
Q	.209	.224	5.31	5.69	
S	.217 BSC		5.51 BSC		

LEAD ASSIGNMENTS

HEXFET

1.– GATE
2.– DRAIN
3.– SOURCE
4.– DRAIN

IGBTs, CoPACK

1.– GATE
2.– COLLECTOR
3.– EMITTER
4.– COLLECTOR

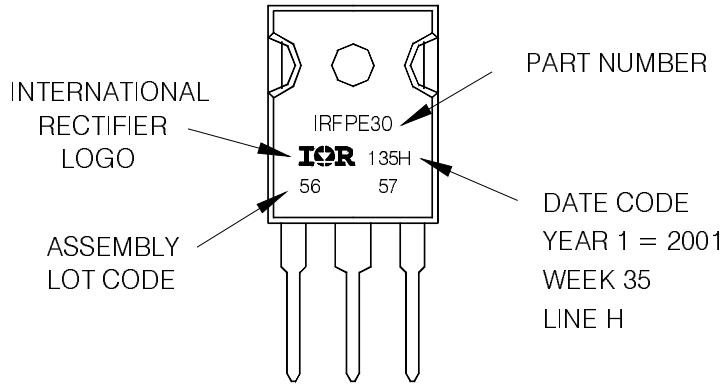
DIODES

1.– ANODE/OPEN
2.– CATHODE
3.– ANODE

TO-247AC Part Marking Information

EXAMPLE: THIS IS AN IRFPE30
WITH ASSEMBLY
LOT CODE 5657
ASSEMBLED ON WW 35, 2001
IN THE ASSEMBLY LINE "H"

Note: "P" in assembly line position
indicates "Lead-Free"

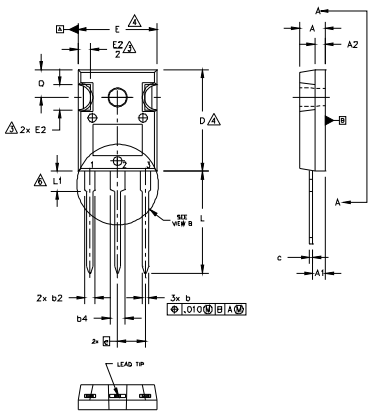


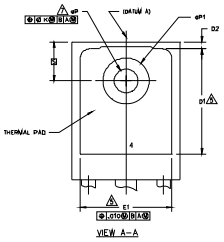
TO-247AC package is not recommended for Surface Mount Application.

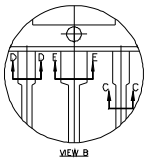
Note: For the most current drawing please refer to IR website at http://www.irf.com/package/

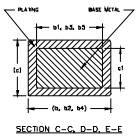
TO-247AD Package Outline

Dimensions are shown in millimeters (inches)









NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M 1994.
2. DIMENSIONS ARE SHOWN IN INCHES.
3. CONTOUR OF SLOT OPTIONAL.
4. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS D1 & E1.
6. LEAD FINISH UNCONTROLLED IN L1.
7. øP TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5 ° TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF .154 INCH.
8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-247AD.

SYMBOL	DIMENSIONS				NOTES
	INCHES		MILLIMETERS		
	MIN.	MAX.	MIN.	MAX.	
A	.183	.209	4.65	5.31	
A1	.087	.102	2.21	2.59	
A2	.059	.098	1.50	2.49	
b	.039	.055	0.99	1.40	
b1	.039	.053	0.99	1.35	
b2	.065	.094	1.65	2.39	
b3	.065	.092	1.65	2.34	
b4	.102	.135	2.59	3.43	
b5	.102	.133	2.59	3.38	
c	.015	.035	0.38	0.89	
c1	.015	.033	0.38	0.84	
D	.776	.815	19.71	20.70	4
D1	.515	–	13.08	–	5
D2	.020	.053	0.51	1.35	
E	.602	.625	15.29	15.87	4
E1	.530	–	13.46	–	
E2	.178	.216	4.52	5.49	
e	.215 BSC		5.46 BSC		
øk	.010		0.25		
L	.780	.827	19.57	21.00	
L1	.146	.169	3.71	4.29	
øP	.140	.144	3.56	3.66	
øP1	–	.291	–	7.39	
Q	.209	.224	5.31	5.69	
S	.217 BSC		5.51 BSC		

LEAD ASSIGNMENTS

HEXFET

1.– GATE
2.– DRAIN
3.– SOURCE
4.– DRAIN

IGBTs, CoPACK

1.– GATE
2.– COLLECTOR
3.– EMITTER
4.– COLLECTOR

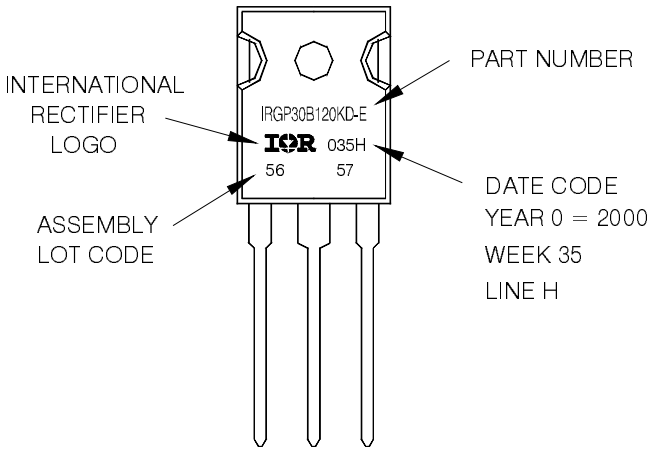
DIODES

1.– ANODE/OPEN
2.– CATHODE
3.– ANODE

TO-247AD Part Marking Information

EXAMPLE: THIS IS AN IRGP30B120KD-E
WITH ASSEMBLY
LOT CODE 5657
ASSEMBLED ON WW 35, 2000
IN THE ASSEMBLY LINE "H"

Note: "P" in assembly line position
indicates "Lead-Free"



TO-247AD package is not recommended for Surface Mount Application.

Note: For the most current drawing please refer to IR website at http://www.irf.com/package/

Data and specifications subject to change without notice.
This product has been designed and qualified for Industrial market.
Qualification Standards can be found on IR's Web site.

International
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IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
TAC Fax: (310) 252-7903
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